

**AMENDMENTS TO THE CLAIMS:**

Claim 1. (Original) An optoelectronic packaging assembly, comprising:

a submount having a cavity defined by a floor, sidewalls, a back wall, and a front wall, wherein at least one of said sidewalls retains pins, said submount further including an optical input receptacle which extends from said front wall;

a base having sidewalls with top surfaces and a front wall with a slot, wherein said base is configured to receive said submount such that said submount extends over said sidewalls of said base and such that said optical input receptacle extends from said slot; and

an external cover over said submount.

Claims 2-75. (Cancelled)